

FIG. 1

200  
FORM FIRST DIELECTRIC LAYER OVER SEMICONDUCTOR SUBSTRATE

~202

FORM FIRST MAGNETIC LAYER OVER FIRST DIELECTRIC LAYER

~204

PATTERN FIRST MAGNETIC LAYER TO DEFINE AT LEAST ONE SLOT

~206

FORM SECOND DIELECTRIC LAYER OVER FIRST MAGNETIC LAYER,  
FILLING EACH SLOT IN FIRST MAGNETIC LAYER

~208

PATTERN SECOND DIELECTRIC LAYER  
TO DEFINE AT LEAST ONE VIA TO FIRST MAGNETIC LAYER

~210

FORM CONDUCTIVE LAYER OVER SECOND DIELECTRIC LAYER

~212

PATTERN CONDUCTIVE LAYER  
TO FORM A CONDUCTOR HAVING A SPIRAL-SHAPED SIGNAL PATH  
AND TO CLEAR ANY VIAS TO FIRST MAGNETIC LAYER

~214

FORM THIRD DIELECTRIC LAYER OVER CONDUCTIVE LAYER

~216

PATTERN THIRD DIELECTRIC LAYER  
TO DEFINE AT LEAST ONE VIA TO FIRST MAGNETIC LAYER

~218

FORM SECOND MAGNETIC LAYER OVER THIRD DIELECTRIC LAYER,  
FILLING ANY VIAS TO FIRST MAGNETIC LAYER

~220

PATTERN SECOND MAGNETIC LAYER TO FORM AT LEAST ONE SLOT

~222

FIG. 2

0085370.051101

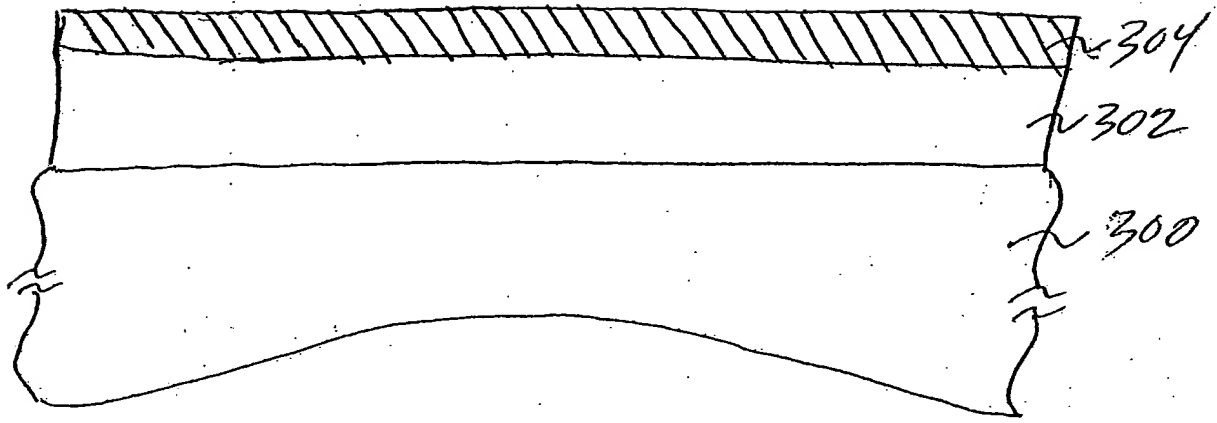


FIG. 3

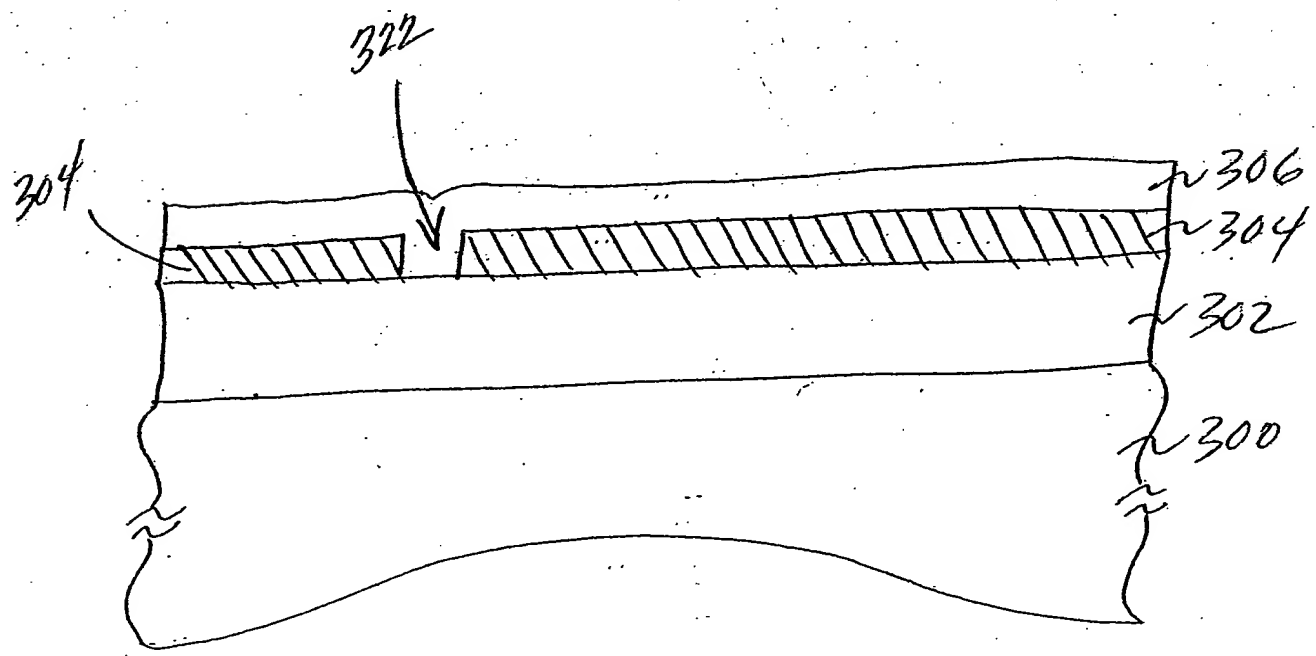


FIG. 4

09853370.051101

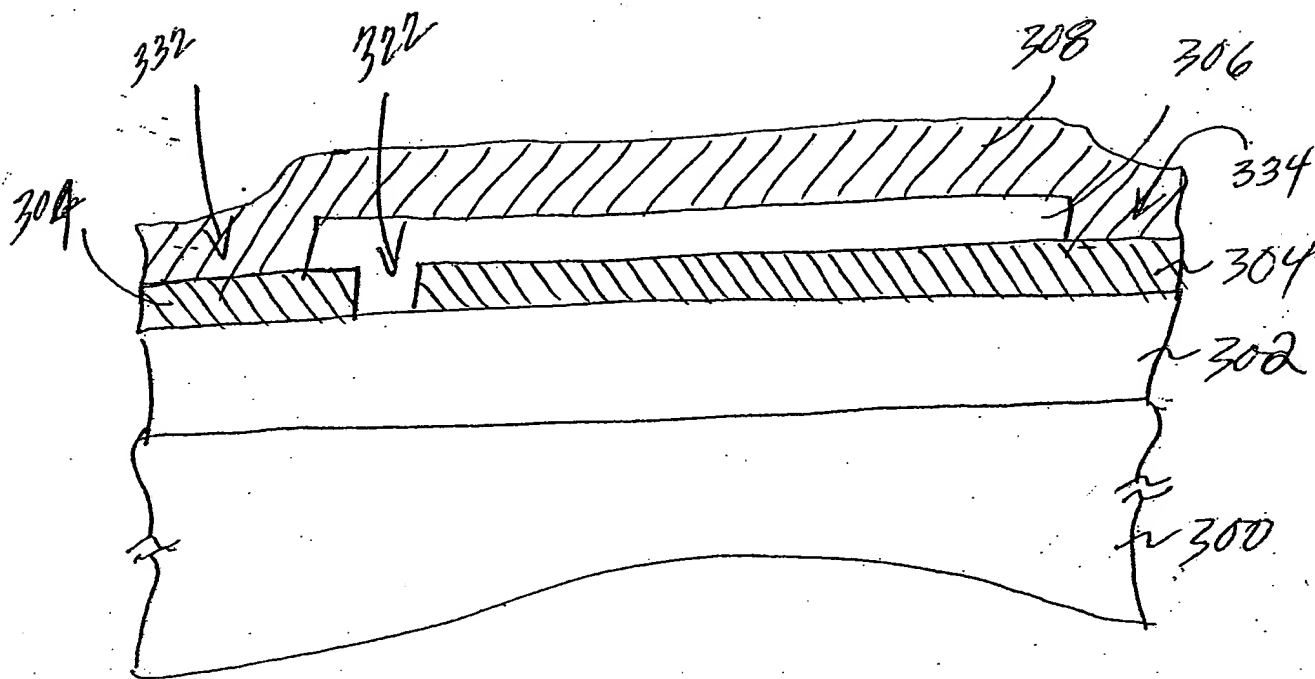


FIG. 5

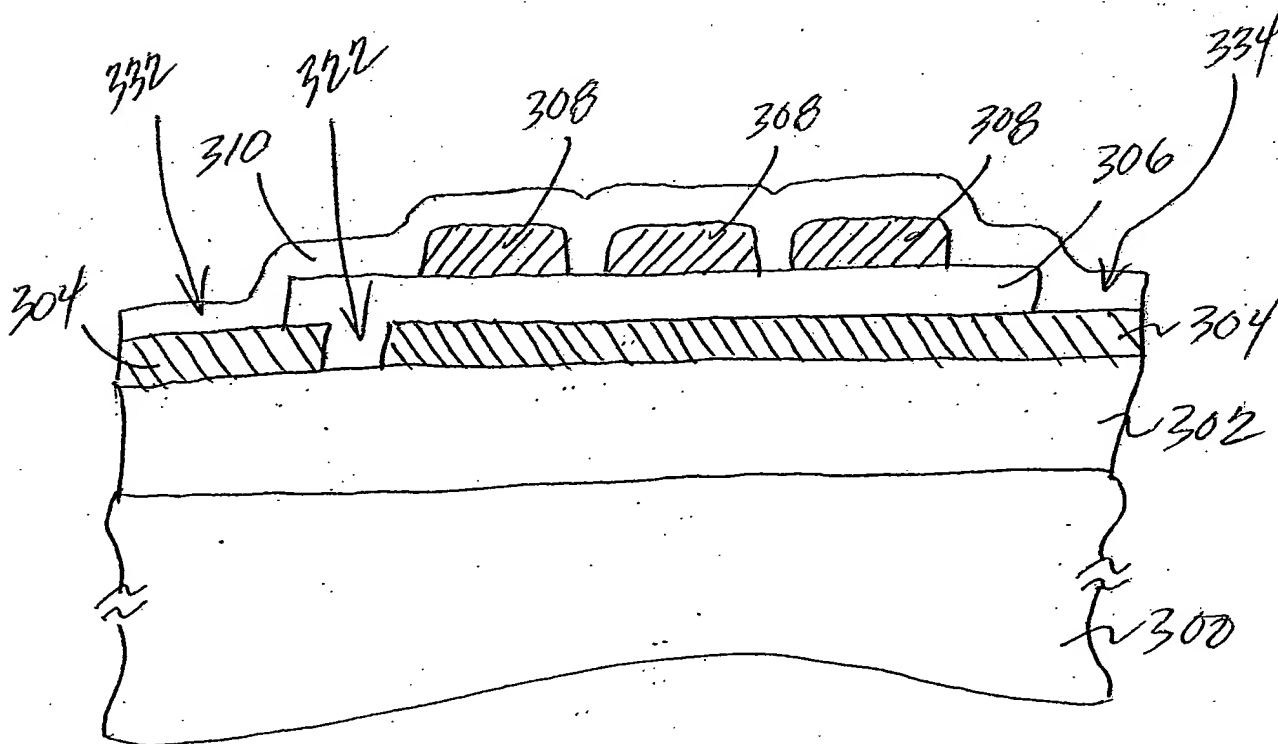


FIG. 6

A cross-sectional view of a multi-layered structure. The structure consists of several layers and components. At the bottom is a thick, wavy line representing a substrate or base layer, labeled 300. Above this is a layer labeled 302. The next layer is labeled 304. Above 304 is a layer labeled 306. The topmost layer is a complex structure with multiple layers and features. It includes a layer labeled 310, which is part of a larger assembly labeled 312. Within this assembly, there are several rectangular blocks labeled 308. The top surface of the assembly is labeled 332. The side surface of the assembly is labeled 334. The bottom surface of the assembly is labeled 342. The entire structure is shown in a cross-sectional view, with hatching used to indicate different materials or layers.

Fig. 7

0985370.051401

900

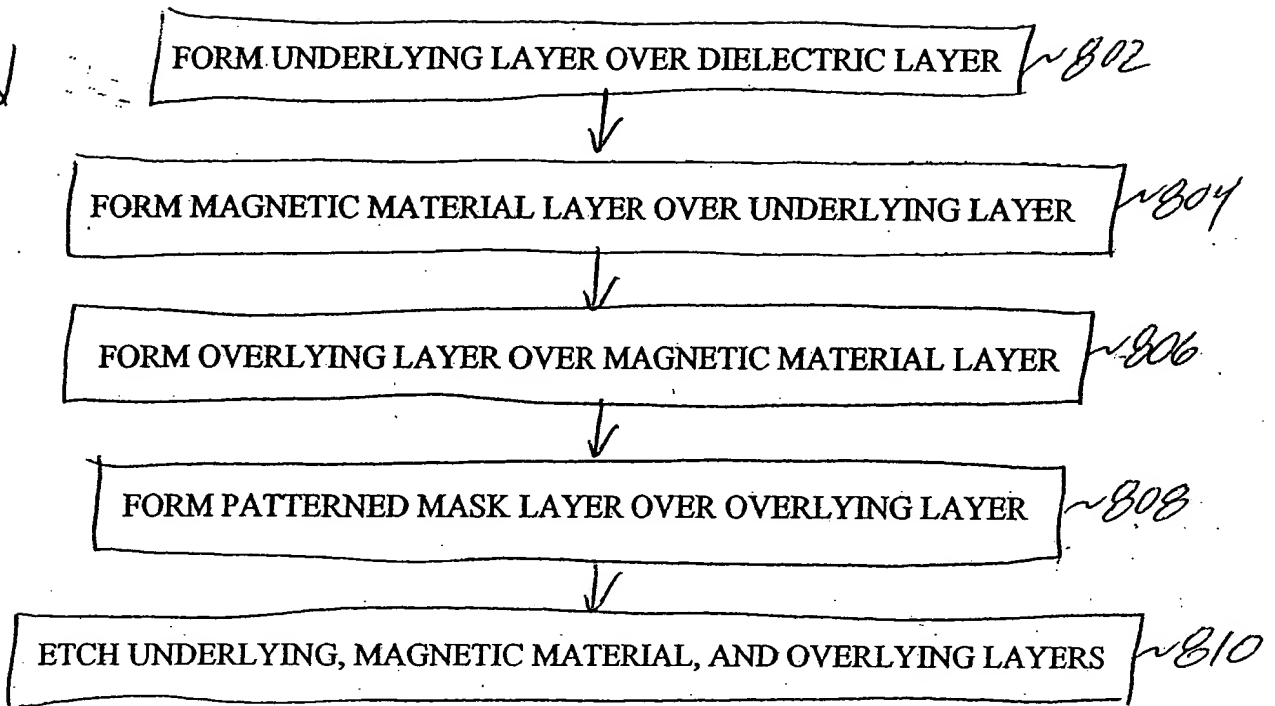


FIG. 8

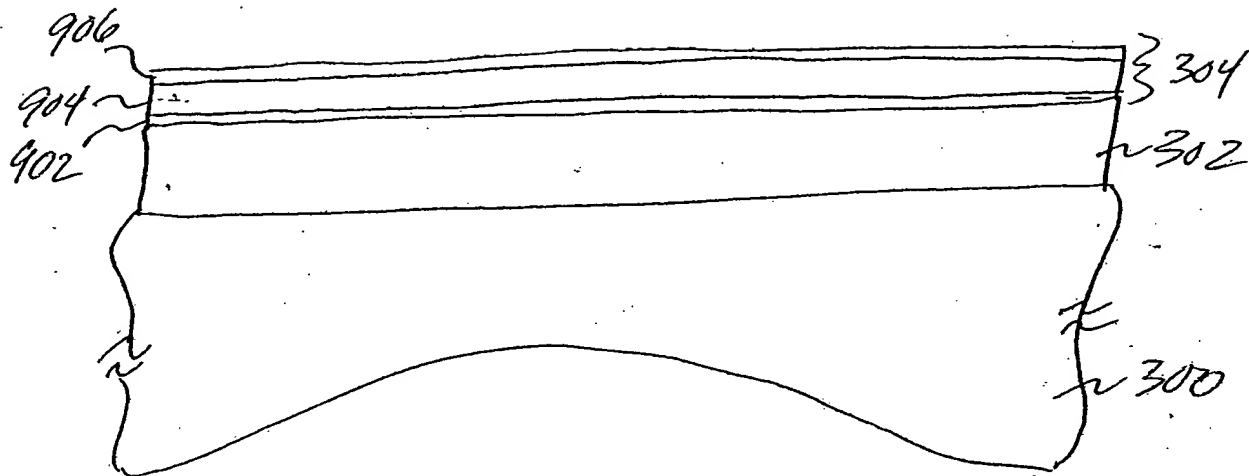


FIG. 9

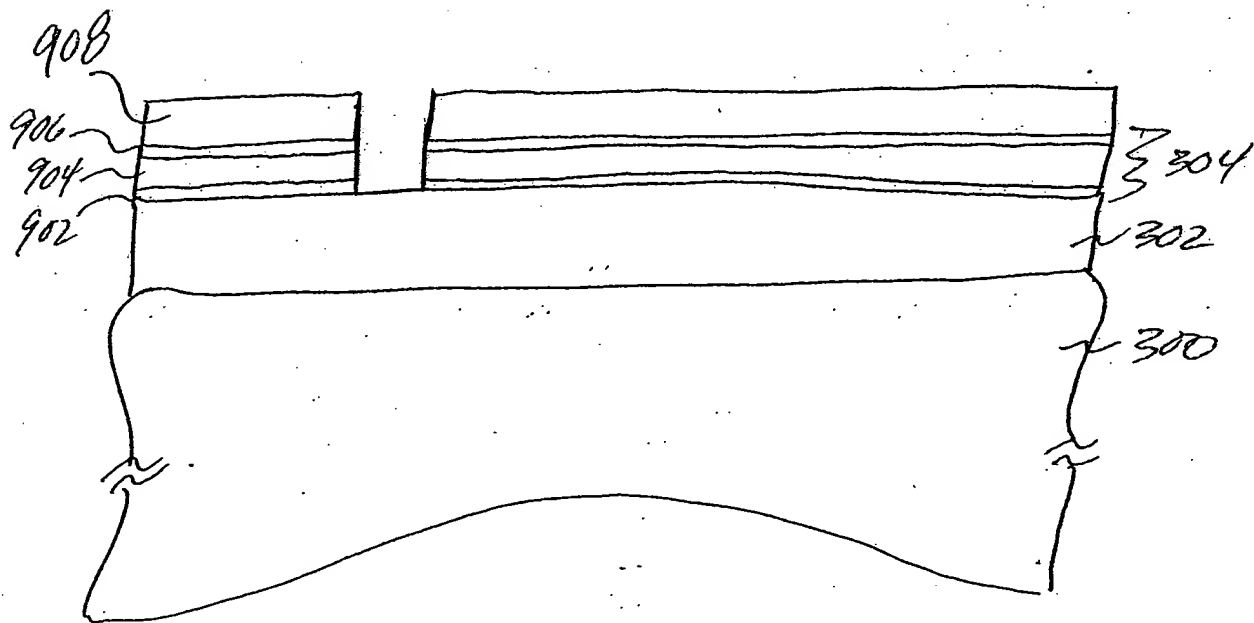


FIG. 10

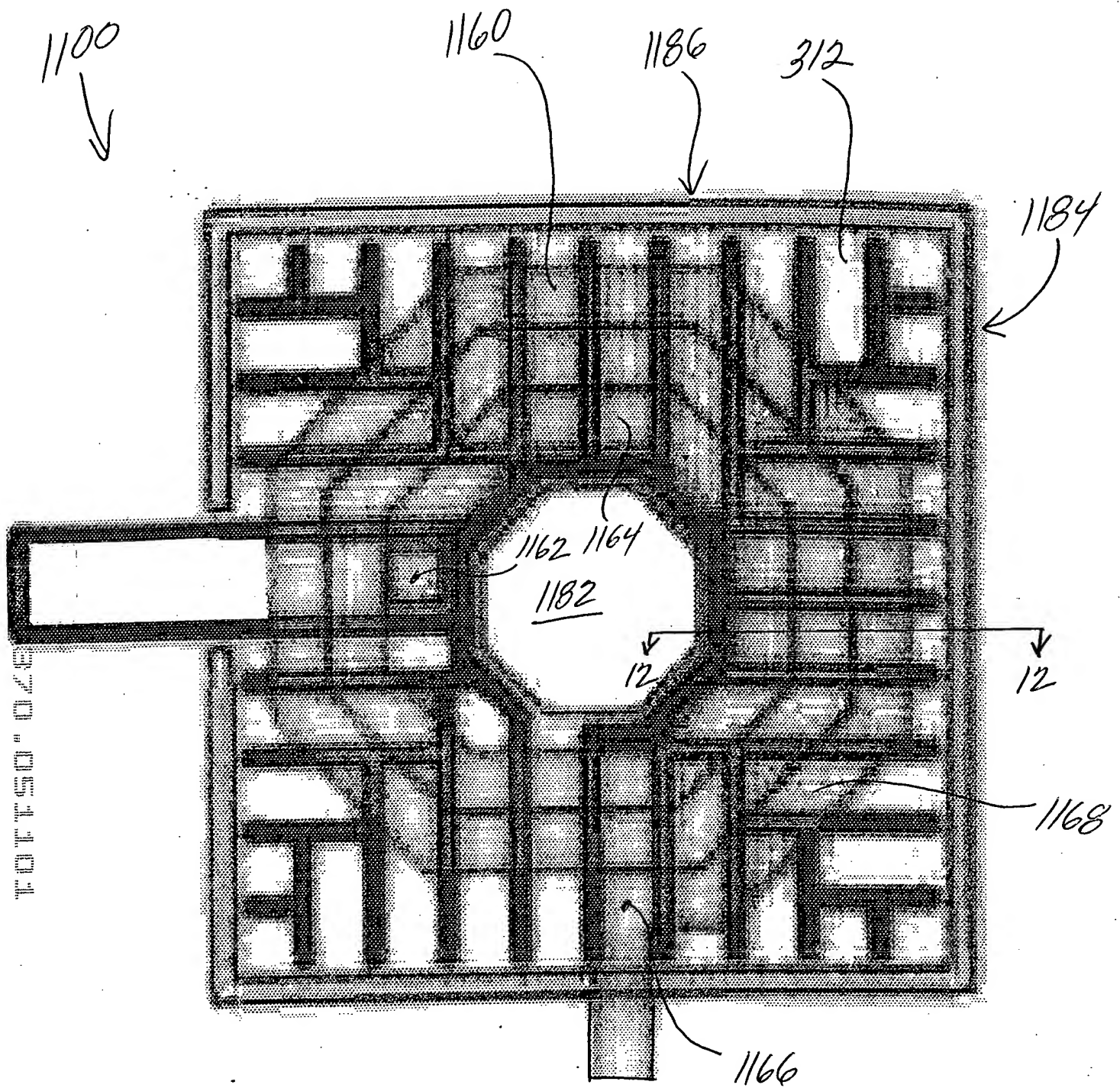


FIG. 11



FIG. 12

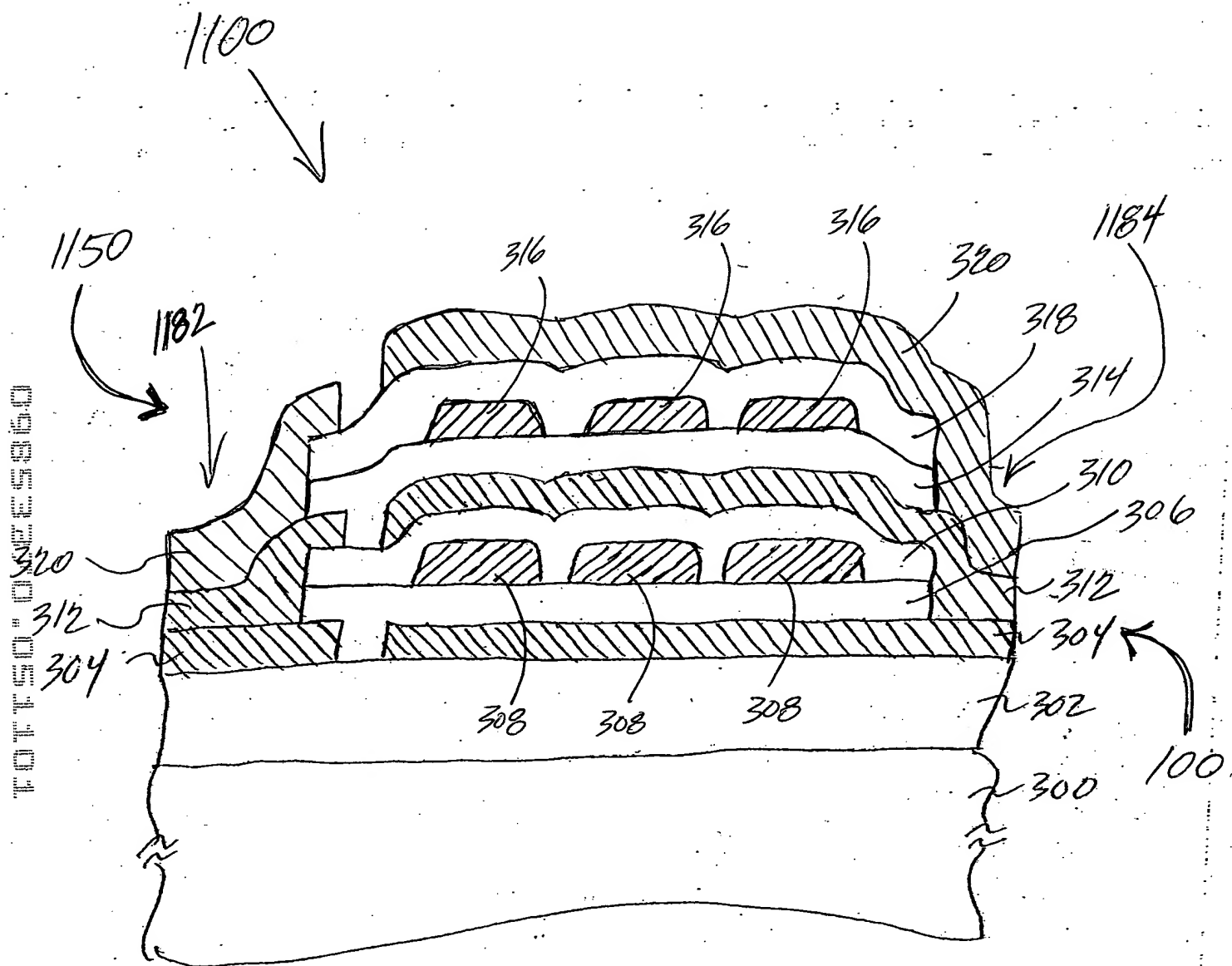


FIG. 12

FIG. 13

1300

1310

1360

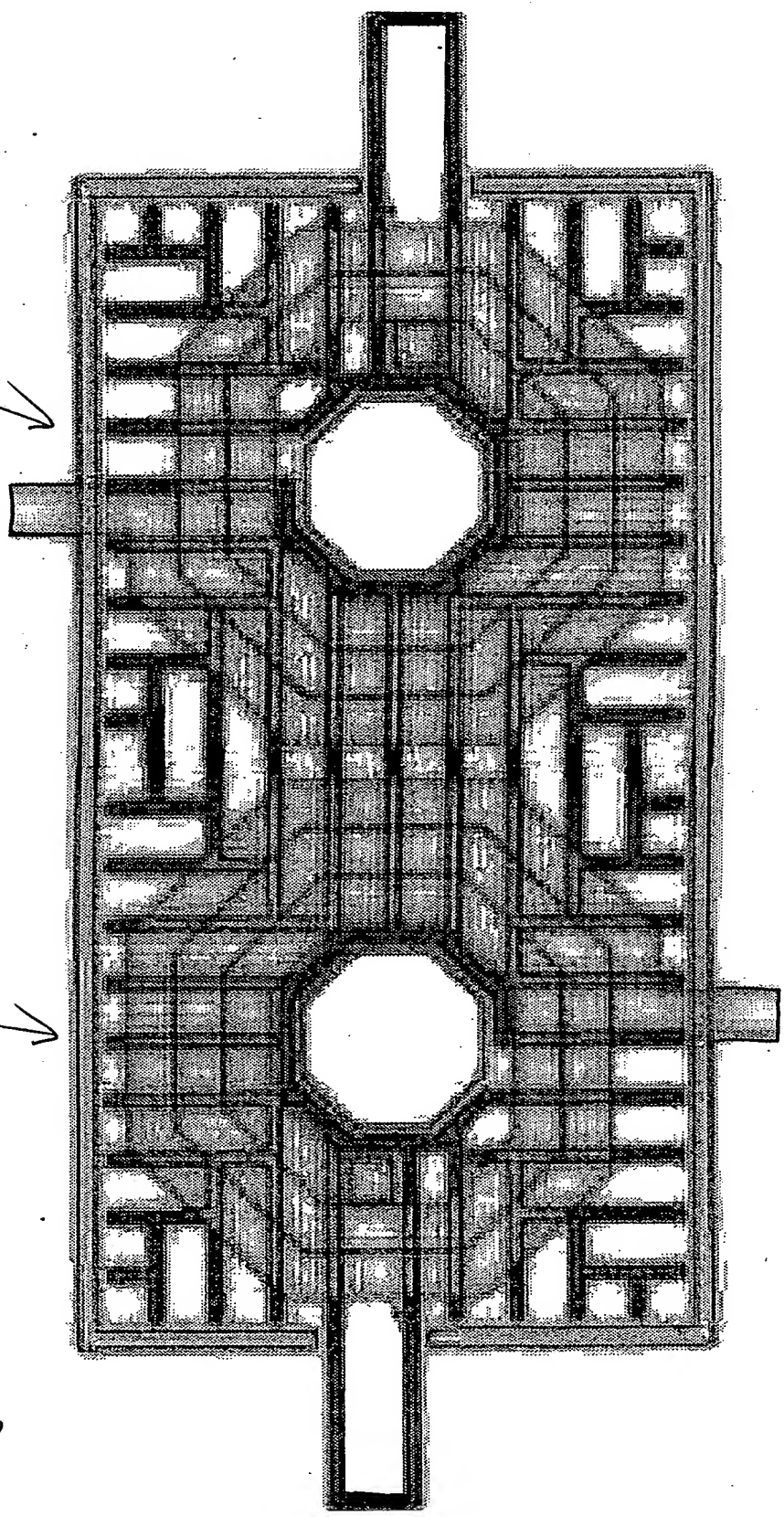


FIG. 13

FIG. 14

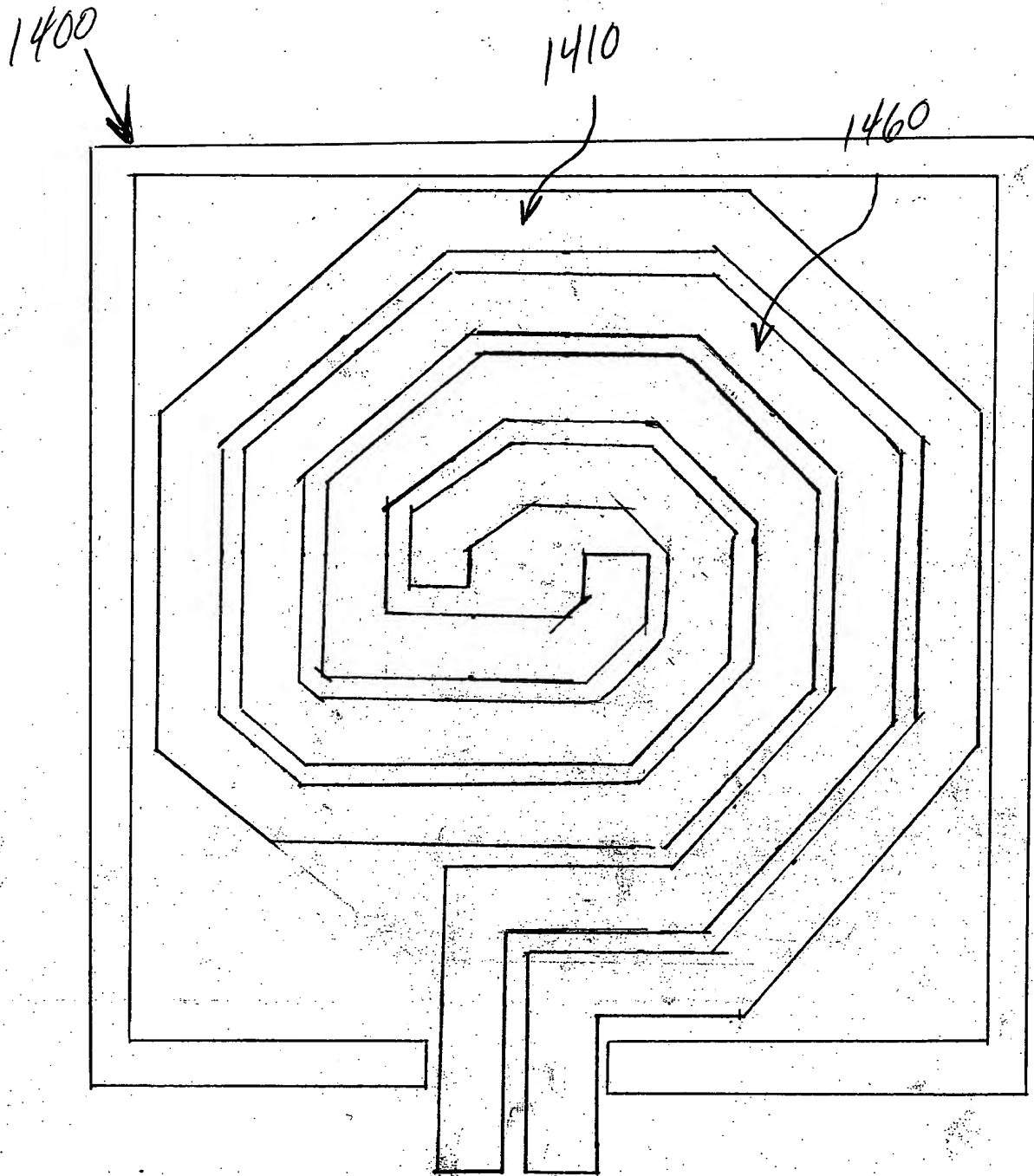


FIG. 14

095370.05.10.1

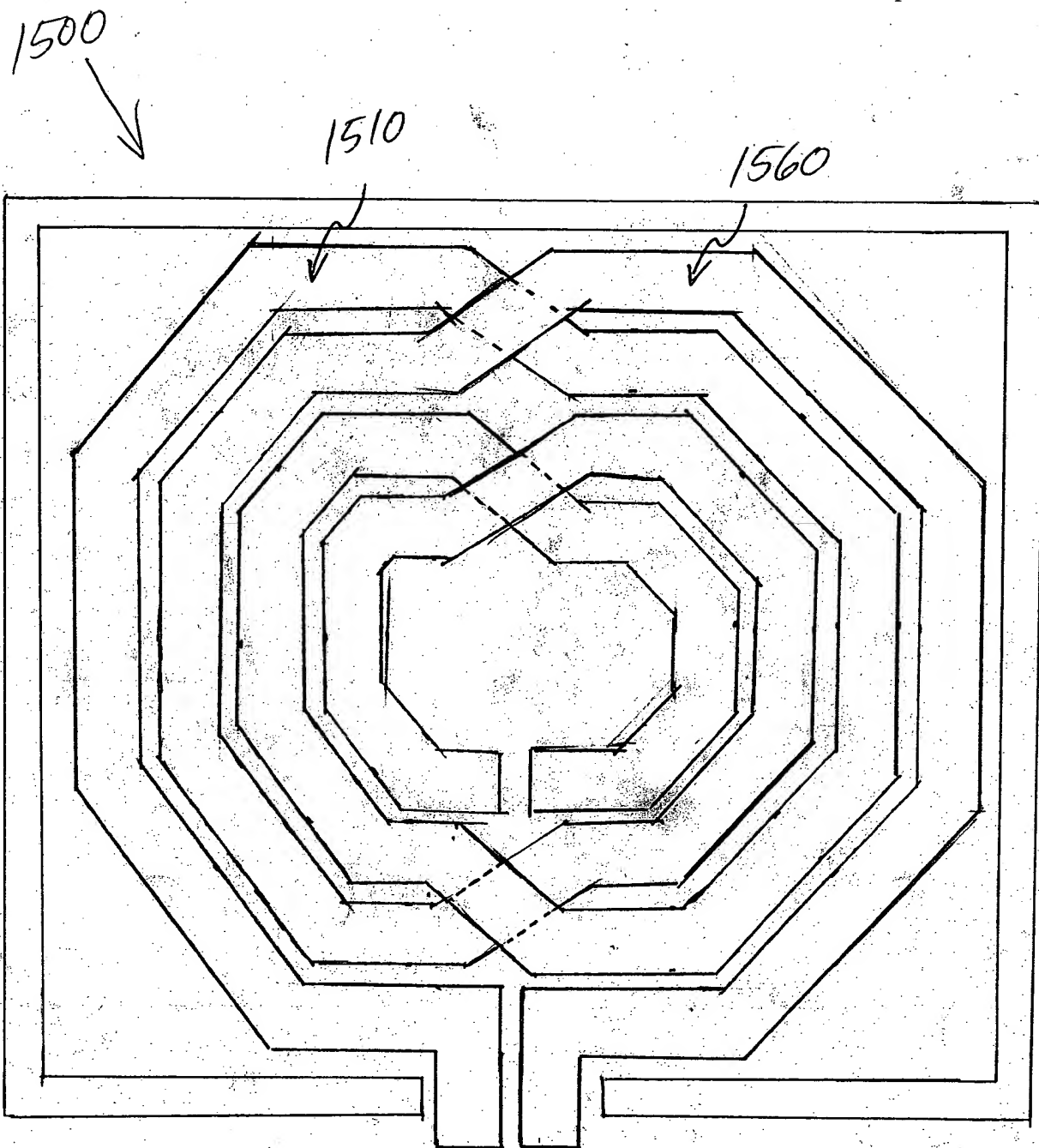


FIG. 15

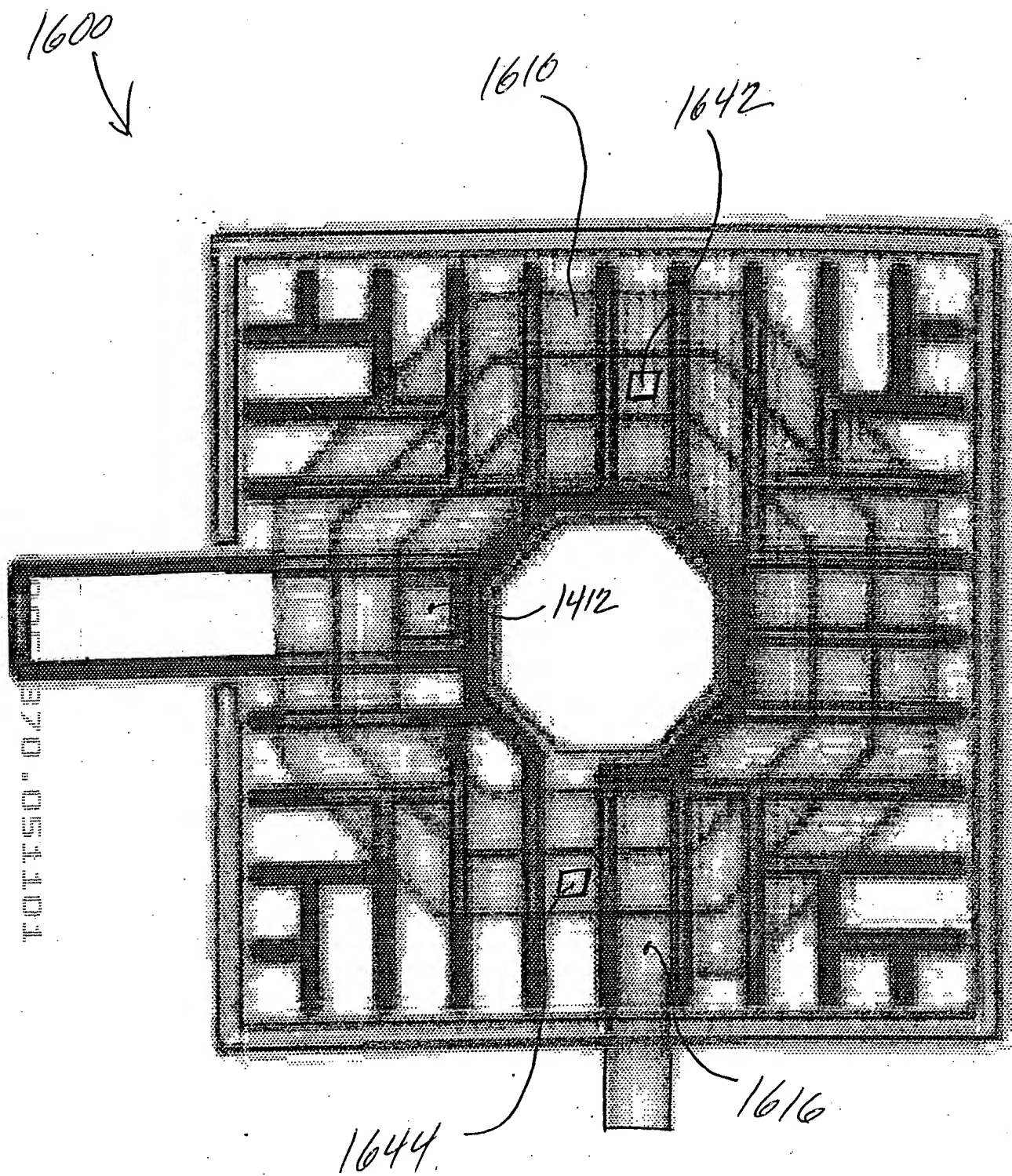


FIG. 16

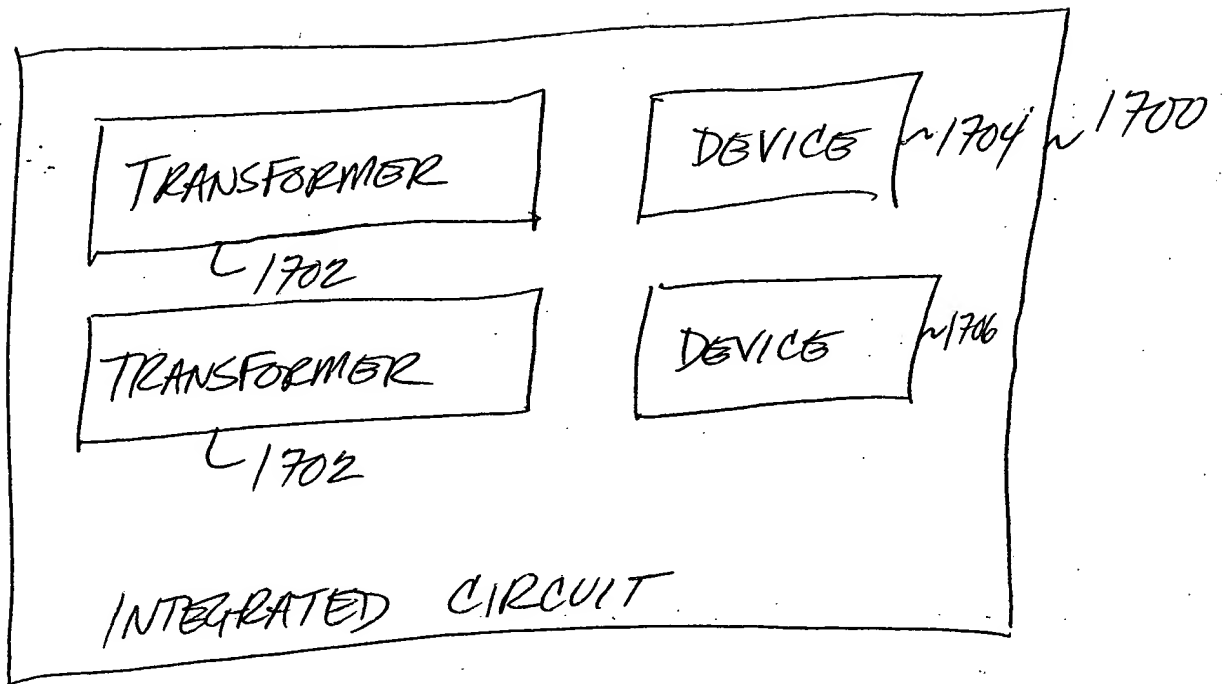


FIG. 17

0955370-051401

1800 ~

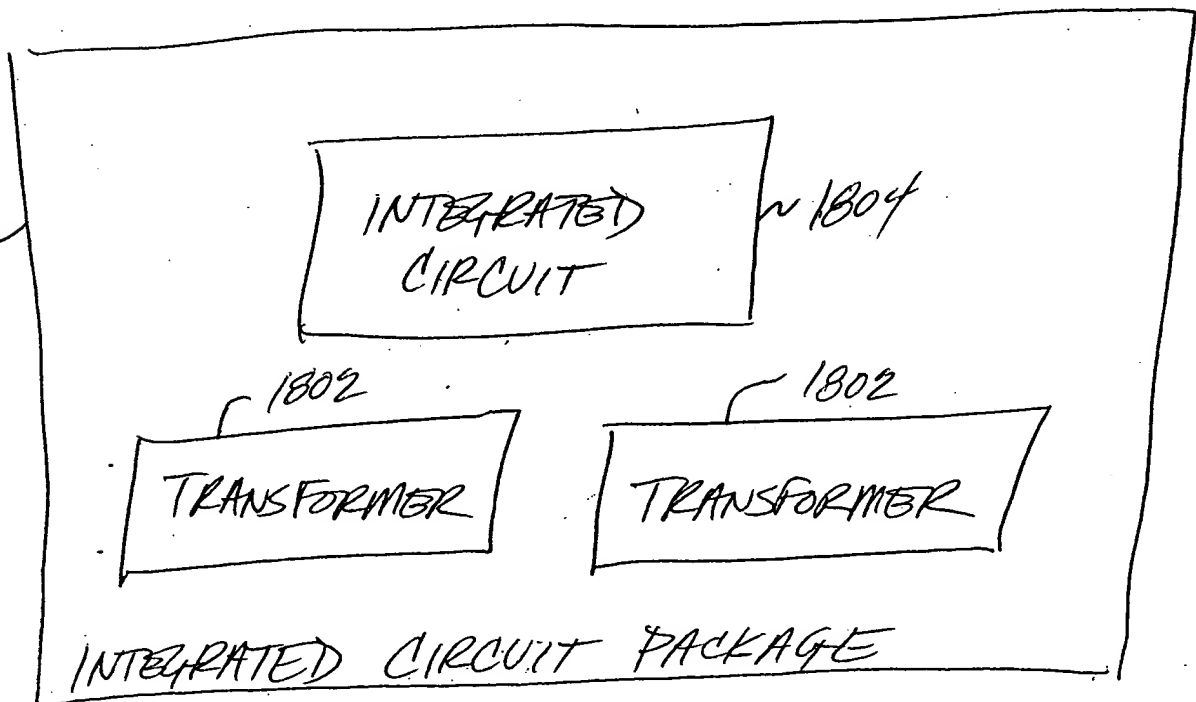


FIG. 18